AN13264

i.MX RT1170 Dual Core Application

Rev. 0 — 27 April, 2021 Application Note

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1 Introduction

This document introduces the dual-core application on i.MX RT1170, including the following topics:

- Boot
- Brief introduction to MU/SEMA4/RDC/XRDC2/Shared memory
- · Dual-core debug in different tool chain

2 Boot

2.1 Boot from CM7

By default, i.MX RT1170 boots from CM7 core. This chapter discusses how to boot CM4 when CM7 core is the boot core.

2.1.1 Basic model for understanding how to boot the second core

At first, we need to know a basic model to understand how to boot the second core, as shown in Figure 1.



Figure 1 shows the basic steps to boot the second core (CM4):

- 1. CM7 loads the image into CM4 ITCM.
- 2. CM7 kicks off CM4.
- 3. CM4 core is running.

On i.MX RT1170, CM4 ITCM has two address, <code>0x1FFE_0000</code> and the alias of <code>0x2020_0000</code>.

- 0x1FFE_0000 is for CM4 ITCM access. Only CM4 core can use this base address and the CM4 code image uses this address for instruction storage.
- 0x2020_0000 is for alias access with slow speed. Both CM7 and CM4 can access this base address. CM7 loads CM4 image to CM4 ITCM with this address.

2.1.2 Detailed Boot flow

The detailed boot flow is as below:

- 1. Prepare CM4 image. Typically, it is placed inside CM7 image. It can also be from other source like SD card, or U-disk, and so on.
- 2. After CM7 core runs, CM7 core loads the CM4 image into target memory. Typically, for CM7, it is the space 0x2020 0000 which maps to CM4 ITCM.



- CM7 core sets the vector table address of CM4 by IOMUXC_LPSR_GPR -> GPR0 and IOMUXC_LPSR_GPR -> GPR1.
- 4. Kick off CM4 core by SRC_SCR_BT_RELEASE_M4_MASK.

2.1.3 Loading CM4 image into target memory

To load the CM4 image into target memory, use either way as below:

- Load explicitly, using the memcpy() function.
- · Load implicitly, similar to initializing some variables in RAM.

For different IDE/Tool chain, SDK uses different way. It is controlled by macro <code>core1_image_copy_to_ram</code>. MCUXpresso uses implicit way and IAR, KEIL and GCC uses explicit way.

For more details about boot from CM7, refer to SDK example at SDK root/boards/evkmimxrt1170/multicore_examples/hello_world

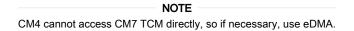
2.2 Boot from CM4

By default, i.MX RT1170 boot from CM7. By fusing BT_CORE_SEL (Bit 12 in 0x960), the chip switches to CM4 as main core.

The steps to boot from CM4 are as below, similar to booting from CM7.

- 1. CM4 loads CM7 image into target memory.
- 2. Release CM7 core.
- 3. CM7 core is running.

The difference is that CM7 vector table is loaded from IOMUXC_LPSR_GPR -> GPR26 and the release from CM7 is by SRC_SCR_BT_RELEASE_M7_MASK. For more details, see the mcmgr_start_core_internal() function in mcmgr_internal_core_api_imxrt1170.c.

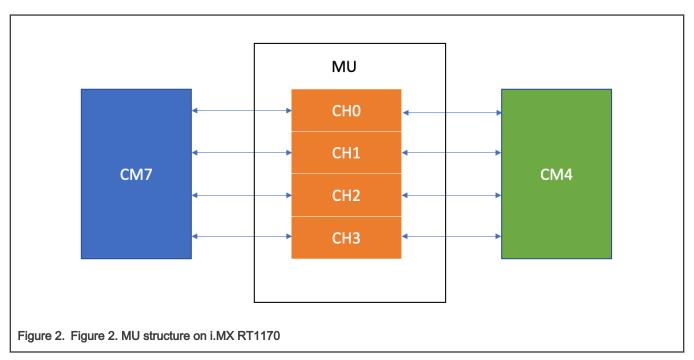


As NXP official SDK package only supports CM7 as main core (boot core), the enablement for this case is limited. Do not switch to CM4 as main core if it is not a must in application.

3 Brief introduction to MU/SEMA4/RDC/XRDC2/Shared memory

3.1 MU

By MU, one core can give a 32-bit message to the other, and trigger interrupt of the other immediately. It supports four bi-directional channels. Figure 2 shows the MU structure.



For example, CM7 can give a $0x1234_5678$ message to CM4, and then CM4 can catch the $0x1234_5678$ message in an interrupt immediately.

For related SDK example, see SDK root/boards/evkmimxrt1170/driver_examples/mu.

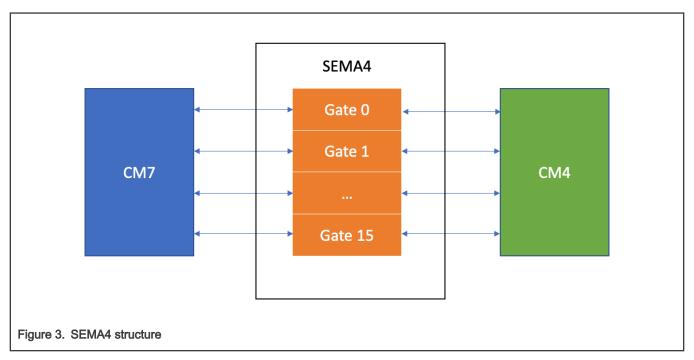
3.2 SEMA4

SEMA4 is typically used for resource protection in multi-core environment, to prevent different masters using one resource at the same time.

The resource can be a memory block, a peripheral or even an SW object in memory.

The SEMA4 supports up to 16 gates. Only the master who locks the gate successfully, getting the sema4, can use the resource protected by this SEMA4 gate. Other masters have to wait until the master who owns the gate releases/unlocks this gate.

Figure 3 shows the SEMA4 structure.



For related SDK example, see SDK root/boards/evkmimxrt1170/driver_examples.

3.3 RDC/XRDC2

RDC/XRDC2 is used for resource isolation. The resource can be peripheral or memory. The privilege can be read, written or both read and written.

For example, we can assign LPUART1 to CM7 domain, and then only CM7 core can access LPUART1. If other bus master like CM4 core accesses LPUART1, violation ISR happens.

NOTEBus masters for RDC/XRDC2 are not limited to CM7 and CM4 core, ENET, LCDIF, USB, CSI and so on, are also bus masters.

3.4 Shared memory

Shared memory can be accessed by both CM7 and CM4 core. If a data block needs to be passed from one core to the other core, shared memory with MU can be a good candidate.

The typical working flow is as below:

- 1. A core write a block data into B core.
- 2. After Step 1 completes, A core trigger B core MU interrupt, and B core knows there is data block from A core ready.
- 3. B core read the data block and process.
- 4. After Step 3 completes, B core trigger A core MU interrupt, and A core knows B core has processed the data block, and then A core can load the next data block for B core.

If necessary, double buffer and even a queue can be used.

Table 1 lists typical memory which can be used as shared memory.

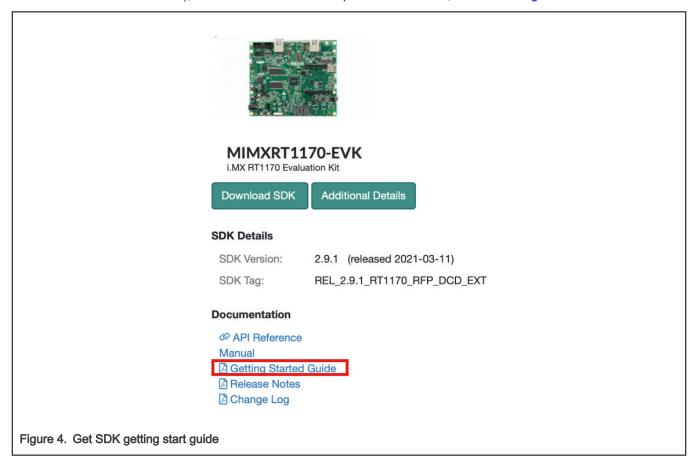
Table 1. Typical memory which can be used for shared memory

| | Access address for CM7 | Access address for CM4 | Size |
|------------|------------------------|------------------------|--------|
| CM4 DTCM | 0x2022_0000 | 0x2000_0000 | 128 KB |
| OCRAM1 | 0x2024_0000 | Same as CM7 | 512 KB |
| OCRAM2 | 0x202C_0000 | Same as CM7 | 512 KB |
| OCRAM1_ECC | 0x2034_0000 | Same as CM7 | 64 KB |
| OCRAM2_ECC | 0x2035_0000 | Same as CM7 | 64 KB |

In addition, external memory from SEMC, like SDRAM and memory from Flex SPI, can also be used as shared memory if necessary.

4 Dual-core debug in different tool chain

For the guide to dual-core debugging, see *Getting Started with MCUXpresso SDK for MIMXRT1170-EVK* (document MCUXSDKMIMXRT117XGSUG), which is available on MCUXpresso SDK Builder, as shown in Figure 4.



See the sections related to multi-core to know how to start a dual-core debugging on RT1170 for *MCUXpresso/IAR/Keil/GCC*. This document also introduces some key points for dual core debugging for user reference.

4.1 MCUXpresso

Test environment:

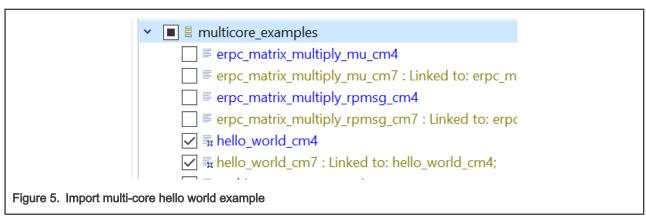
- SDK: 2.9.1 for i.MX RT1170
- MCUXpresso: 11.3.1
- Example: SDK_root|boards|evkmimxrt1170|multicore_examples|hello_world

4.1.1 By DAP-LINK (CMSIS DAP)

Set the board to XIP boot mode by setting **SW1** to **OFF OF ON OFF**. Make sure there is a known image in the flash which is working correctly. Some bad images will block debugger connections.

Quick steps for MCUXpresso dual core debug:

1. Import multi-core hello world example, as shown in Figure 5.



- 2. Build the CM4 project.
- 3. Build the CM7 project.
- 4. Select the CM7 project.

```
Project Explorer 
Project 
Project Explorer 
Project Explorer 
Project Explorer 
Project 
Project Explorer 
Project 
Project Explorer 
Project 
Pro
```

- 5. Start debug session by click the 🔅 button.
- 6. Select CMSIS DAP debugger for CM7 and CM4 separately in Figure 7.

| | Name | Serial number/ID | Туре | Manufacturer | IDE Debug Mode |
|------|---------------------|-----------------------|------------|--------------|----------------|
| LS | CMSIS-DAP v1 | 02440b03092db67700000 | LinkServer | ARM | Non-Stop |
| Link | J-Link PLUS | 600109557 | USB | SEGGER | All-Stop |
| Link | 3rd party CMSIS-DAP | 1043579317 | USB | SEGGER | All-Stop |

7. Then CM7 stops at main.

```
le hello_world_core0.c 
| hello_world_core1.c | hello_world_core1
```

8. Click the



button.

- 9. CM4 core stops at main.
- 10. Click the Run button in CM4 core project and both cores are running. The console log is as below:

```
Hello World from the Primary Core!
Starting Secondary core.
The secondary core application has been started.
```

11. In the **Debug** window, both cores are running. We can select either core and stop it for debugging, or if there is user break point, it hits once the code runs to the breakpoint.

```
# Debug 

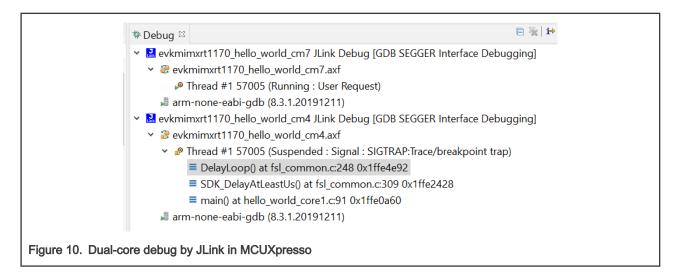
Continued by the property of the pr
```

4.1.2 By JLink

Set the board to XIP boot mode by setting SW1 to OFF OFF ON OFF.

For JLink debugger, un-populate J5-J8. Steps for CMSIS DAP are same, and the below only lists the different steps:

- 1. Select CM7 project and start debug session.
- 2. Run CM7 project, while CM4 project will not be attached automatically.
- 3. Attach CM4 project.
 - a. Select CM4 project.
 - b. Click the 💠 button.
- 4. The dual-core debug is enabled.



4.2 IAR

Test environment:

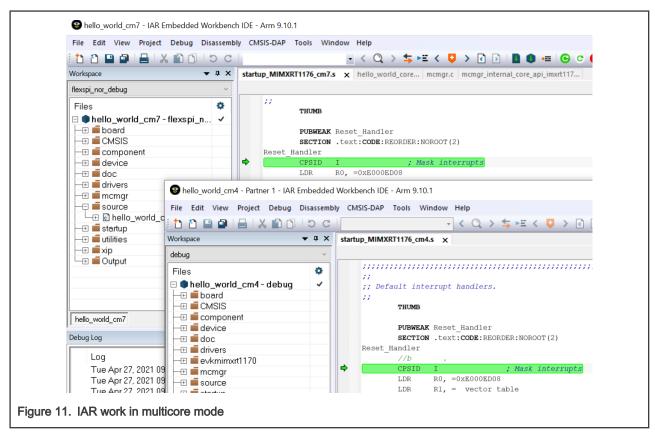
- SDK: 2.9.1 for i.MX RT1170
- IAR: 9.10.1
- Example: SDK_root|boards|evkmimxrt1170|multicore_examples|hello_world

4.2.1 By DAP-LINK (CMSIS DAP)

Quick steps for IAR dual core debug are as below:

- 1. Build the CM4 project.
- 2. Build the CM7 project.
- 3. In the CM7 project, start the debug session by click the button

Then both CM7 and CM4 projects are launched for debugging automatically by IAR in multicore mode.



- 4. Run CM7 core in the CM7 project.
- 5. Run CM4 core in the CM4 project.

4.2.2 By JLink

Set the board to XIP boot mode by setting SW1 to OFF OFF ON OFF.

For JLink, IAR does not support multicore mode like what it supports for DAP-Link. We need to open CM7 project and CM4 project separately for dual-core debugging.

The steps for dual core debug by JLink are as below:

- Build CM4 and CM7 projects.
- 2. Start CM7 debug session.
- 3. Run the CM7 project.
- 4. Attach CM4 project, as shown in Figure 12.

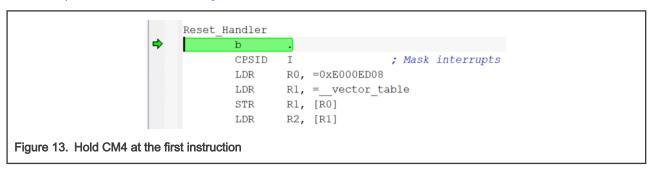


5. Press the unbutton if necessary, and the code stops where it is running.

4.2.3 Debug CM4 core from the first instruction

By default, CM4 core debugging cannot start from the beginning. To debug CM4 from the first instruction, follow steps as below.

1. Add an loop instruction as shown in Figure 13.



2. When CM4 core project is loaded correctly, the code breaks here. Move PC to the next instruction by right-clicking next instruction → **Set next statement** command.



Now, we can debug from the first application instruction.

4.3 Keil

Test environment:

- SDK: 2.9.1 for i.MX RT1170
- Keil: 5.34
- Example: SDK_root|boards|evkmimxrt1170|multicore_examples|hello_world

4.3.1 By DAP-LINK(CMSIS DAP)

Set the board to XIP boot mode.

Follow the steps as below for dual-core debugging:

- 1. Build the CM4 project.
- 2. Build the CM7 project.
- 3. Start the CM7 debug session.

4. Attach the CM4 project by clicking the **(1)** button.

4.3.2 By Jlink

Set the board to XIP boot mode by setting SW1 to OFF OFF ON OFF.

Follow the steps below for dual-core debugging:

- 1. Copy evkmimxrt1170\multicore_examples\hello_world\cm7\evkmimxrt1170_connect_cm4_cm7side.jlinkscript to mdk folder and rename it to JLinkSettings.jlinkscript.
- 2. Copy evkmimxrt1170\multicore_examples\hello_world\cm4\evkmimxrt1170_connect_cm4_cm4side.jlinkscript to mdk folder and rename it to JLinkSettings.jlinkscript.
- 3. Build the CM4 project.
- 4. Build the CM7 project.
- 5. Start the CM7 debug session but do not run.
- 6. Start the CM4 debug session.
- 7. Run the CM7 project.

4.3.3 Debug CM4 core from the first instruction.

For details, see Debug CM4 core from the first instruction and one difference is to select Set Program Counter after right click.

5 References

- i.MX RT1170 Processor Reference Manual (document IMXRT1170RM)
- Getting Started with MCUXpresso SDK for MIMXRT1170-EVK (document MCUXSDKMIMXRT117XGSUG)

6 Revision history

| Revision number | Date | Substantive changes |
|-----------------|----------------|---------------------|
| 0 | 27 April, 2021 | Initial release |

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